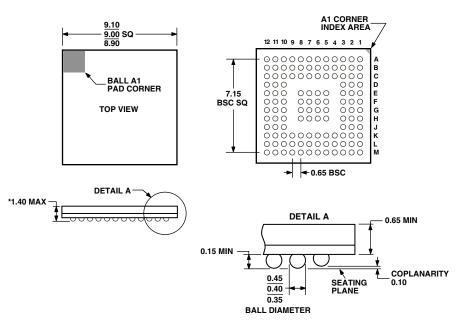


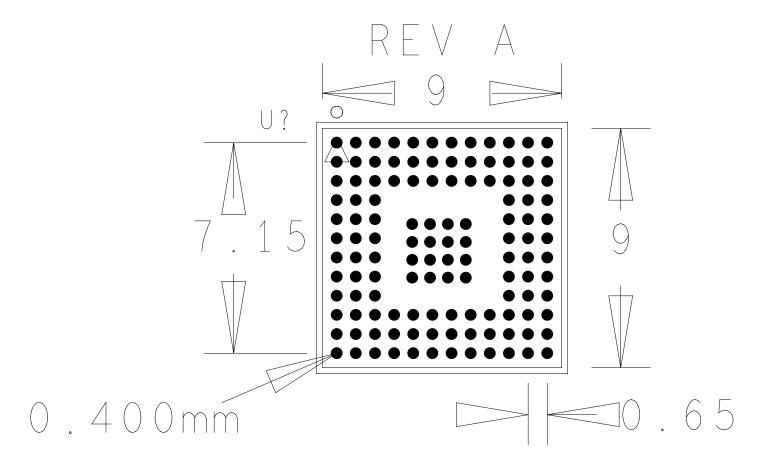
124-Lead Chip Scale Package Ball Grid Array [CSP_BGA] (BC-124-1)

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-225 WITH THE EXCEPTION OF PACKAGE HEIGHT.

Analog Devices BC-124-1



(Dim. are in MM)
LAST MODIFIED 06/07/07